

### C. Remarks

The claims are 1-6 and 11-13, with claims 1, 11, 12 and 13 being independent. The independent claims have been amended to recite additional features of the present invention.<sup>1</sup> Support for the amendment may be found, inter alia, in the specification at page 6, line 26-page 7, line 1; pages 8, lines 5-6 and 10-12; and page 14, lines 1-3. No new matter has been added. Reconsideration of the present claims is expressly requested.

Claim 13 is objected to under 37 C.F.R. § 1.75 for being a substantial duplicate of claim 12. Applicants respectfully disagree.

Claim 12 is directed to a method for forming an electroconductive member. Claim 13 is directed to a method for forming an electrode and wiring. It is clear that these claims are different in scope (e.g., there are many electroconductive members, which are not an electrode and wiring) even though the explicitly recited steps are the same. As stated in M.P.E.P. 706.03(k), a difference in scope between the claims is sufficient to comply with the requirements of 37 C.F.R. § 1.75. Therefore, it is respectfully requested that this objection be withdrawn.

Claims 1 and 11-13 stand rejected under 35 U.S.C. § 102(e) as being allegedly anticipated by U.S. Patent Application Publication No. 2003/0026959 A1 (Furuse '959). Claims 2-6 stand rejected under 35 U.S.C. § 103(a) as being allegedly unpatentable over Furuse '959 in view of U.S. Patent No. 6,586,155 B2 (Furuse '155). The grounds of rejection are respectfully traversed.

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<sup>1/</sup> Applicants stress that this amendment is not to be construed as an acquiescence with the Examiner's allegations made in the Office Action.

Prior to addressing the merits of rejection, Applicants would like to briefly review some of the features of the presently claimed invention. That invention is related, in part, to a method for forming an electrode and wiring. In this method, a photosensitive resin containing a water-soluble photosensitive resin component and a water-soluble metallic compound is applied onto the substrate and exposed. The exposed photosensitive resin is developed to form on the substrate a base pattern, which contains at least one water-soluble metallic compound. Subsequently, an organic metallic compound, which contains a metal different from that in the water-soluble metallic compound, is absorbed into the base pattern. The base pattern, in which the organic metallic compound is absorbed, is baked at a temperature of 400-600°C.


Furuse '959 is related to a method for forming a metal or a metal compound pattern by using a solution containing metal components. This document does not disclose absorbing in the developed base pattern an organic metallic compound that contains a different metal from that already applied to the substrate prior to exposing and developing the resin.

Furuse '155 relates to a composition for forming an electro-conductive film. However, Furuse '155, lacks the same disclosure mentioned above that is missing in Furuse '959. Thus, neither Furuse '959 nor Furuse '155, whether considered separately or in combination, can affect the patentability of the presently claimed invention.

Wherefore, Applicants respectfully request that the outstanding rejections be withdrawn and that the present case be passed to issue.

Applicants' undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should continue to be directed to our address given below.

Respectfully submitted,



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